

**LIQUID RESIN COMPOSITION, SEMICONDUCTOR CHIP WITH AN ADHESIVE
LAYER, METHOD OF PRODUCING SUCH MATERIALS, AND
SEMICONDUCTOR DEVICES**

ABSTRACT OF THE DISCLOSURE

A liquid resin composition includes (A) an epoxy resin component and (B) a
curing agent component, the epoxy resin component (A) being liquid at room
5 temperature, and the curing agent component (B) including (B1) a compound which has
phenolic hydroxyl group(s) and is dissolvable in the epoxy resin component (A), and
(B2) a compound which has hydroxyl group(s) and is not dissolvable in the epoxy resin
component (A).

NO SUITABLE FIGURE